TE0955 TRM

Revision v.7

Exported on 2026-08-13

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4 Overview

The Trenz Electronic TE0955 is an AMD Versal AI Edge SoC based System on Module (SoM).

The SoC combines a dual core Arm Cortex-A72 Application Processor, a dual core Arm Cortex-R5F Real Time Processor, a FPGA and an AI Engine Machine Learning (AIE-ML).

The module integrates the SoC's two Quad GTYP transceivers, DDR4LP SDRAM, SPI Flash memory for configuration and operation, a Gigabit Ethernet PHY, a USB 2.0 PHY and powerful switch-mode power supplies for all on-board voltages. A large number of configurable I/Os is provided via rugged B2B connectors.

Refer to http://trenz.org/te0955-info for current online available documentation.

4.1 Key Features

- **SoC**
  - AMD Versal
    - AI Edge: VE2202 / VE2302 [1)]
    - Prime: VM1102 [1)]
  - Speedgrade: -1 / -2 / -3 [1)]
  - Temperature Range: Extended / Industrial [1)]
  - Package: SFVA784
- **RAM/Storage**
  - 8 GByte LPDDR4 [2)]
  - 256 MByte OSPI Flash (with XiP support) [2)]
  - 32 GByte e.MMC [2)]
  - EEPROM with unique EUI-48 Ethernet MAC and 192 Byte usable storage
- **On Board**
  - 10/100/1000 BASE-T/X Ethernet Transceiver (TSN, PTP)
  - USB 2.0 Transceiver
  - OPTIGA™ Trust M Security Element
  - CryptoAuthentication™ Device
  - Trusted platform module (TPM)
  - Clocks for SoC PL, PS, DDR4 and PHYs
- **Interface**
  - Trenz 4 x 5.64 SoM 2x B2B Connector (Samtec ADM6) socket:
    - **MIO:** 24x SE
    - **XPIO:** 58x SE / 27x DIFF / 4x MIPI
    - **HDIO:** 22x SE / 11x DIFF / 2x MIPI
    - **GTYP:** 8x MGT and 4x CLK
  - Andromeda standard form factor compatible
- **Power**
  - Single 12V power supply
- **Dimension**
  - 40 mm x 56.4 mm
- **Notes**

  [1)] Available as assembly variant or upon request.

  [2)] Other sizes/devices, which are pin/package-compatible, upon request.

4.2 Block Diagram

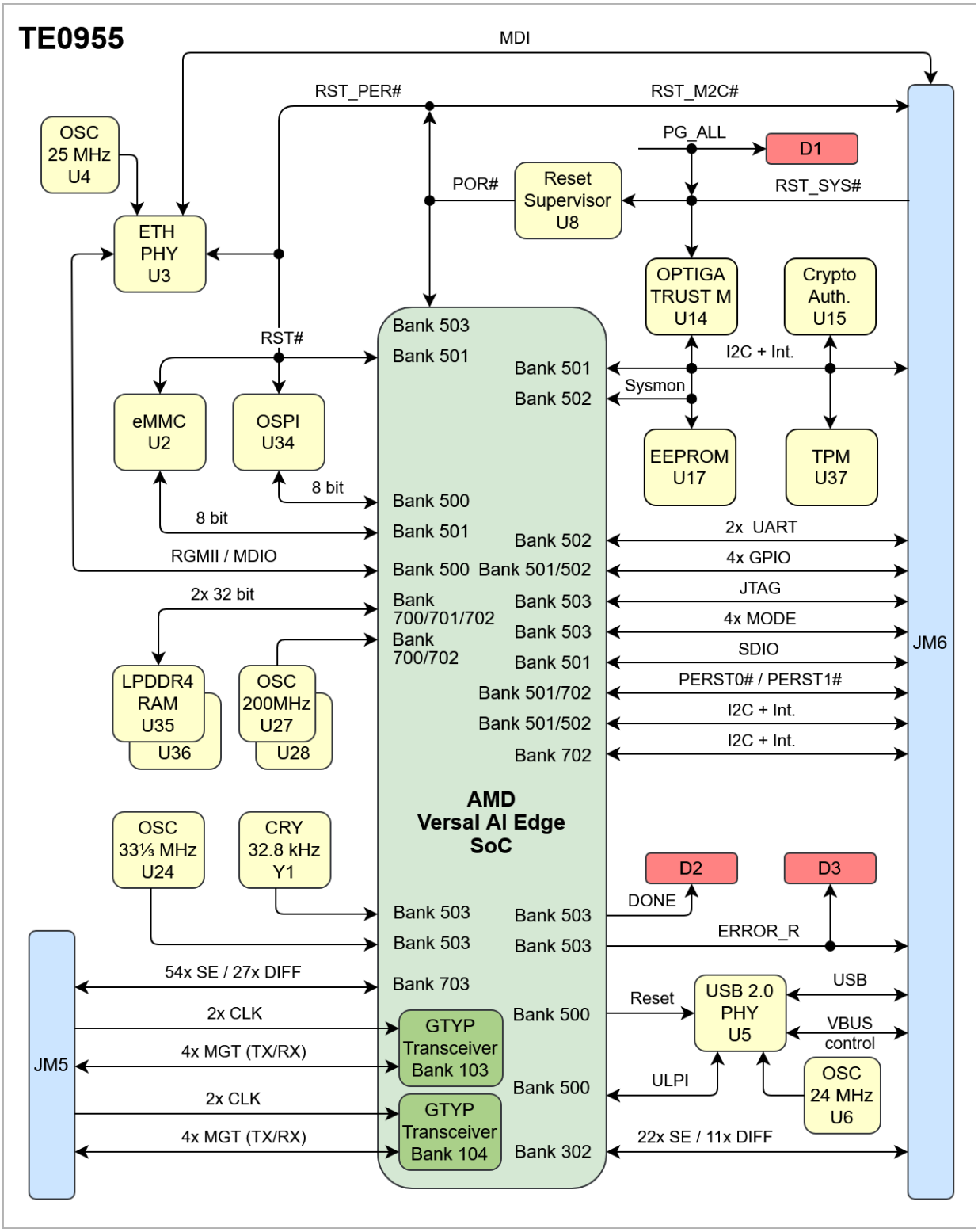

Figure 1: TE0955 block diagram

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4.3 Main Components

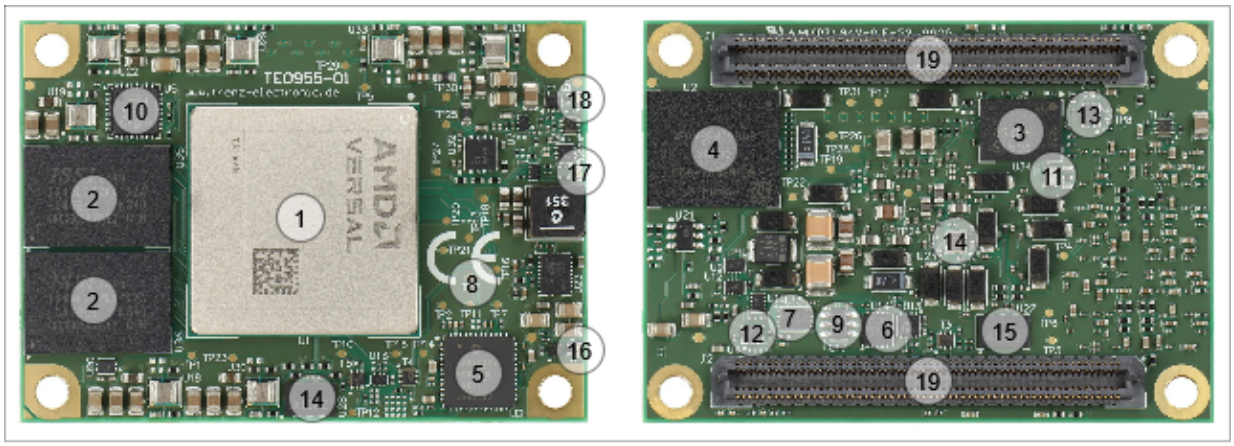
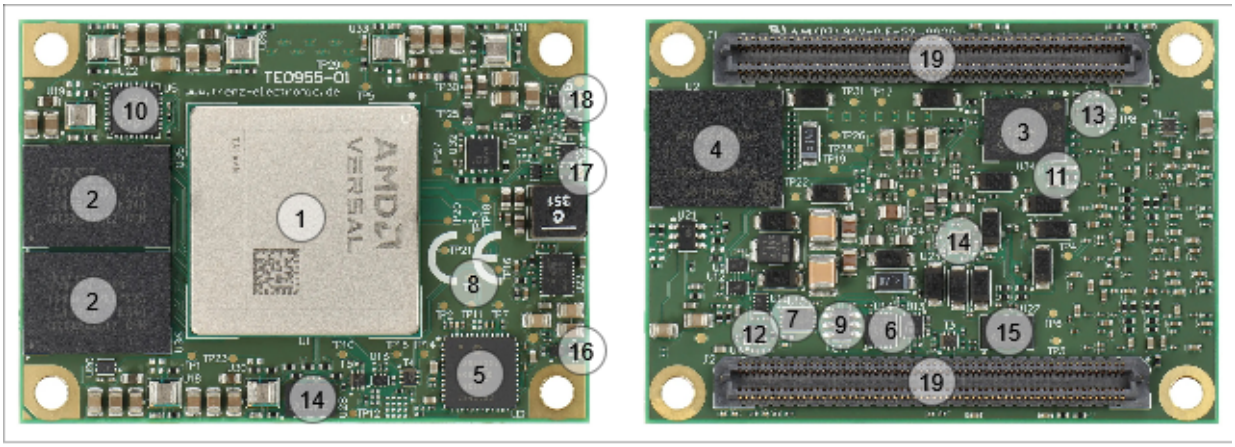


Figure 2: TE0955 main components (Underlying Pictures are REV01)



1. Versal Adaptive SoC, U1
2. LPDDR4, U35, U36
3. OSPI NOR Flash, U34
4. e.MMC, U2
5. Ethernet PHY, U3
6. OPTIGA™ Trust M Security Element, U14
7. CryptoAuthentication™ Device, U15
8. Trusted Platform Module (TPM) U37
9. Serial EEPROM with 48bit MAC, U17
10. USB 2.0 Transceiver, U5
11. Crystal, Y1
12. Oscillator for Ethernet 25 MHz, U4
13. Oscillator for USB 24 MHz, U6
14. Oscillator for SoC 33 MHz Bank 503, U24
15. Oscillator for LPDDR4 200 MHz, U27, U28
16. LED red, signals PG_ALL, D1
17. LED red, signals initialisation DONE, D2
18. LED red, signals V_ERROR, D3
19. B2B, JM5, JM6

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4.4 Initial Delivery State

Storage device name	Content	Notes
Octal SPI Flash, U34	Not programmed	
e.MMC, U2	Not programmed	
EEPROM, U17	Manufacturer programmed MAC	
LPDDR4 SDRAM, U35, U36	Not programmed	

Table 1: Initial delivery state of programmable devices on the module

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5 Signals, Interfaces and Pins

5.1 Connectors

Connector Type	Designator	Interface	IO count	Notes
B2B	JM5	IO HP	54x SE / 27x DIFF	Bank 703
B2B	JM5	MGT	8x GTYP	Banks 103 & 104
B2B	JM5	MGT CLK	4x GTYP CLK	Banks 103 & 104
B2B	JM6	IO HD	22x SE / 11x DIFF	Bank 302
B2B	JM6	ETH MDI	8x DIFF	Bank 502
B2B	JM6	ETH PHY LED	2x SE	Bank 502
B2B	JM6	SDIO	11x SE	Bank 501
B2B	JM6	GPIO	4x SE	Bank 501 & 502
B2B	JM6	USB 2.0	1x DIFF	Bank 500

Table 2: Board Connectors

5.2 Test Points

Test Point	REV02				REV01 Signal
	Top	Bottom	Notes	Signal	
TP1	x			3V3_AO	
TP2	x			DDR_1V1	

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Test Point	REV02				REV01 Signal
	Top	Bottom	Notes	Signal	
TP3		x		3V3_AO	
TP4		x		DDR_1V1	
TP5	x			3V3	
TP6		x		3V3	
TP7	x			1V8	
TP8		x		1V8	
TP9	x			OM_SCL	
TP10	x			TDI	
TP11	x			OM_SDA	
TP12	x			TDO	
TP13	x			GND	
TP14	x			TCK	
TP15	x			TMS	
TP16	x			V_IO_CFG	
TP17		x		GND	
TP18	x			V_VCC_CORE	
TP19		x		V_VCC_CORE	
TP20	x			V_FUSE	

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Test Point	REV02				REV01 Signal
	Top	Bottom	Notes	Signal	
TP21	x			V_VCC_SOC	
TP22		x		V_VCC_SOC	
TP23	x			V_VCCAUX	
TP24		x		V_VCCAUX	
TP25	x			GTYP_AVCC	
TP26		x		GTYP_AVCC	
TP27	x			GTYP_AVCC_AUX	
TP28		x		GTYP_AVCC_AUX	
TP29	x			PG_ALL	
TP30	x			GTYP_AVTT	
TP31		x		GTYP_AVTT	
TP32	x			TPM_PP	Not used

Table 3: Test Points Information

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6 On-board Peripherals

Chip/Interface	Designator	Connected To	Notes
SoC	U1	• Ethernet PHY • USB PHY • JM5, JM6 • I2C	
LPDDR4	U35, U36	• SoC	
OSPI	U34	• SoC	
eMMC	U2	• SoC	
Ethernet PHY	U3	• SoC • JM6 • Oscillator	Supports TSN, PTP
OPTIGA™ Trust M Security Element	U14	• SoC • JM6 • I2C	
CryptoAuthentication™ Device	U15	• SoC • JM6 • I2C	
Trusted Platform Module	U37	• SoC • JM6 • I2C	
EEPROM with MAC	U17	• SoC • JM6 • I2C	

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Chip/Interface	Designator	Connected To	Notes
USB PHY	U5	• Oscillator	
Chrystal	Y1	• SoC	Default assembly 32.768 kHz.
Oscillator	U24	• SoC	Default assembly 33⅓ MHz.
Oscillator	U27	• SoC LPDDR4 Bank	REF CLK for Memory controller. Default assembly 200 MHz.
Oscillator	U28	• SoC Bank 702	User PL clock Default assembly 200 MHz.
Oscillator	U4	• Ethernet PHY	Default assembly 25 MHz.
Oscillator	U6	• USB PHY	Default assembly 24 MHz.

Table 4: On board peripherals

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7 Configuration and System Control Signals

Signal Name	Connector.Pin	Direction	Description
JTAG(TDI / TCK / TDO / TMS)	JM6.D51 / JM6.D52 / JM6.D54 / JM6.D55	Signal dependent	SoC JTAG.
UART0_RX / UART0_TX	JM6.B49 / JM6.B50	Signal dependent	Software implementation dependent. Alternative GPIO/I2C1_SCL/ CAN_FD_1_TX (no pull-up at SoM). Alternative GPIO/I2C1_SDA/ CAN_FD_1_RX (no pull-up at SoM).
UART1_RX / UART1_TX	JM6.A49 / JM6.50	Signal dependent	Software implementation dependent. Alternative GPIO/I2C1_SDA/ CAN_FD_1_RX (no pull-up at SoM). Alternative GPIO/I2C1_SCL/ CAN_FD_1_TX (no pull-up at SoM).
I2C(M_INT# / M_SCL / M_SDA)	JM6.C49 / JM6.C50 / JM6.C51	Signal dependent	Software implementation dependent.
I2C(U_SCL / U_SDA / U_INT#)	JM6.D33 / JM6.D34 / JM6.D35	Signal dependent	Software implementation dependent.
USB0_ID / USB0_CPEN / V_USB0	JM6.47 / JM6.C48 / JM6.D46	Signal dependent	Software implementation dependent.
PERST0# / PERST1#	JM6.B51 / JM6.B52	INOUT	Intended for use as PCIe reset signal from PL or PS side of the SoC. Can be used as IO pin.
PWR_EN	JM6.D58	IN	Enable SoM Power Rails.

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Signal Name	Connector.Pin	Direction	Description
PWR_EN_IO	JM6.D59	OUT	Signals to carrier to enable the IO Voltage Rails.
ERROR_R [2)]	JM6.A39	OUT	The ERROR_OUT pin is an output-only, open-drain signal with a weak internal pull-up and an external pull-up. When an error occurs in the device, the ERROR_OUT signal is put in a High-Z state and pulled High. The specific errors that cause this pin to assert can be determined and programmed by software.
RST_CPU#	JM6.C58	INOUT	Option; connectable to GPIO0
RST_SYS# [2)]	JM6.C59	IN	Signals to carrier Power Good of all voltage converters. Acts as external SoM reset signal when pulled low.
RST_M2C#	JM6.B58	OUT	Signals to carrier a SoM reset event occurs. SoM reset signal for OSPI, e.MMC and Ethernet. Also connected to SoC RST# signal. Option; connectable to GPIO3_LS.
MODE0 / MODE1 / MODE2 / MODE3 [2)]	JM6.C54 / Jm6.C55 / JM6.C56 / JM6.C57	IN	The MODE[3:0] pins are used to select the boot mode for the device. The value of these pins is captured on the rising edge of POR_B. See Boot Modes and Interfaces for available boot mode details.

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Signal Name	Connector.Pin	Direction	Description
DONE [2]	JM6.C53	OUT	The DONE pin is an output-only, open-drain signal with a weak internal pull-up. An external pull-up is recommended. DONE is controlled by the DONE register. After POR, the DONE signal is Low. When the PLM successfully completes the boot sequence, the software sets the [DONE] bit High, which causes the output buffer to float and be pulled High externally.

Table 5: Controller signal.

[1] Direction:

- IN: Input from the point of view of this board.
- OUT: Output from the point of view of this board.
- INOUT: Bidirectional signal.
- Signal dependent: A Signal can have different functions and directions as part of a Bus.

[2] See Introduction to Versal Adaptive SoCs for further insights.

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8 Power and Power-On Sequence

8.1 Power Rails

Power Rail Name / Schematic Name	Connector.Pin	Direction[1)]	Notes
V_MOD1	JM5.A7 / JM5.A15 / JM5.A47 / JM5.A55 / JM5.B5 / JM5.B11 / JM5.B17 / JM5.B45 / JM5.B51 / JM5.B57 / JM6.C5 / JM6.C11 / JM6.C17 / JM6.D7 / JM6.D15	IN	
V_IO_CFG	JM6.C52	IN	
V_IO_W01	JM5.D3 / JM5.D17	IN	
V_IO_X3	JM6.B59	IN	
V_BAT	JM6.A59	IN	
1V8	JM5.C7 / JM5.C15 / JM6.B7 / JM6.B15	OUT	
3V3_AO	JM6.B59	OUT	

Table 6: Module power rails.

[1)] Direction:

- IN: Input from the point of view of this board.
- OUT: Output from the point of view of this board.

8.2 Recommended Power up Sequencing

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Sequence	Net name	Recommended Voltage Range	Pull-up/down	Description	Notes
0	-	-	-	Configuration signal setup.	See Configuration and System Control Signals.
1	V_MOD1	5 V to 12 V	-	Apply power to the SoM.	
2	PWR_EN	-	Pull-up 3.3 V	Enable power to peripheral SoM devices.	
3	PWR_EN_IO	-	Pull-up 3.3 V	When high, apply IO Bank Voltages.	
4	V_IO_CFG V_IO_W01 V_IO_X3	1.71 V to 1.89 V 0.95 V to 1.57 V 1.71 V to 3.399 V	-	Connect IO Bank Voltage power supply.	

Table 7: Baseboard Design Hints

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9 Board to Board Connectors

The 4 x 5.64 modules use Samtec AcceleRate HD High-Density on bottom side.

- 4x ADM6-60-01.5-L-4-2 (legacy) **or** ADM6-60-01.5-L-4-0 (240 pins, 60 per row)
  - Mates with ADF6-60-03.5-L-4-2 (legacy) **or** ADF6-60-03.5-L-4-0

The carriers use Samtec AcceleRate HD High-Density on top side.

- 4x ADF6-60-03.5-L-4-2 (legacy) **or** ADF6-60-03.5-L-4-0 (240 pins, 60 per row)
  - Mates with ADM6-60-01.5-L-4-0 (legacy) **or** ADM6-60-01.5-L-4-2

9.1 Features

- Board-to-Board connector 240-pins, 60 contacts per row
- Pitch: 0.025" (0.635 mm)
- Data Rate:
  - ADM6-XX-XX.X-X-X-2: 56 Gbps
  - ADM6-XX-XX.X-X-X-0: 64 Gbps
- Mates with: ADM6/APF6
- Insulator Material: Black LCP
- Contact Material: Copper Alloy
- Plating: Au or Sn over 50 µ" (1.27 µm) N
- Operating Temperature Range: -55 °C to +125 °C
- Lead-Free solderable: Yes
- RoHS Compliant: Yes

9.2 Connector Mating height

When using the same type on baseboard, the mating height is 5 mm. Other mating heights are possible by using connectors with a different height:

Order number	REF number	Samtec Number	Type	Contribution to stacking height	Comment
30095	REF-30095	ADM6-60-01.5-L-4-2	Module connector	1.5 mm	Standard connector used on modules (legacy)
-	-	ADM6-60-01.5-L-4-0	Module connector	1.5 mm	Alternative connector
31137	REF-31137	ADF6-60-03.5-L-4-2	Baseboard connector	3.5 mm	Standard connector used on carrier (legacy)

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Order number	REF number	Samtec Number	Type	Contribution to stacking height	Comment
-	-	ADF6-60-03 .5-L-4-0	Baseboard connector	3.5 mm	Alternative connector

Table 8: Connectors.
The module can be manufactured using other connectors upon request.

9.3 Connector Speed Ratings

The AcceleRate HD High-Density connector speed rating depends on the stacking height; please see the following table:

Connector	Stacking height	Speed rating
ADM6-XX-XX.X-X-X-2	5 mm	56 Gbps
ADM6-XX-XX.X-X-X-0	5 mm	64 Gbps

Table 9: Speed rating.

9.4 Current Rating

Current rating of Samtec AcceleRate HD High-Density B2B connectors is 1.34 A per pin (4 pins powered).

9.5 Connector Mechanical Ratings

- Shock: 100G, 6 ms Sine
- Vibration: 7.5G random, 2 hours per axis, 3 axes total

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10 Technical Specifications

10.1 Absolute Maximum Ratings *)

Power Rail / Schematic Name	Description	Min	Max	Unit
V_MOD1	SoM power supply	-0.3	18	V
V_IO_CFG	SoC Configuration Bank power supply	0	3.6	V
V_IO_W01	SoC IO Bank 703 power supply	-0.3	1.65	V
V_IO_X3	SoC IO Bank 302 power supply	-0.3	3.63	V
V_BAT	Backup power supply	-0.5	3.63	V

Table 10: Absolute maximum ratings

*) Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, which do not imply functional operation of the device at these or any other conditions beyond those indicated under "Recommended Operating Condition". Exposure to absolute-maximum rated conditions for extended periods may affect device reliability.

10.2 Recommended Operating Conditions

Trenz Electronic classifies modules into temperature range categories by subsumption of its component data (PCB, ICs, connectors, passive components). The temperature ranges are values for ambient air temperature and do not reflect the junction temperature of individual components.

The categories are:

- Modules with commercial (C) temperature grade are equipped with components that cover at least the ambient temperature range of 0 °C to 70 °C.
- Modules with extended (E) temperature grade are equipped with components that cover at least the ambient temperature range of 0 °C to 85 °C.
- Modules with industrial (I) temperature grade are equipped with components that cover at least the ambient temperature range of -40 °C to 85 °C.

These categories do not take into account the entire custom system consisting of:

- Customer SoC design. The allowed main SoC temperature range is specified from the vendor by junction temperature using corresponding classes (C, E, I). See vendor documentation.

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- Cooling solution, active and or passive cooling.
- Climate or environmental conditions besides ambient temperature range.
- Module orientation, neighbouring assemblies, neither other heat sources nor the SoC as heat source to other components.

Classification of the module can be locked up here: Article Number Information i.e.: TExxxx-xx-xx'I'xx, the 'I' indicates that all components are at least in Industrial temperature class.

The temperature of individual components should not exceed the specified range due to self-heating or heating by adjacent components. The actual operating temperature range will depend on the customer design, usage, environment and cooling solution. Consult Cooling Solutions for more information.

10.2.1 Voltage rails

Parameter	Min	Max	Unit	Reference Document
V_MOD1	4.75	12.6	V	See schematic.
V_IO_CFG	1.71	1.89	V	See schematic.
V_IO_W01	0.95	1.575	V	See schematic.
V_IO_X3	1.71	3.399	V	See schematic.
V_BAT	1.215	1.485	V	See schematic.
V1V8	1.71	1.89	V	See schematic.
3V3_AO	3.201	3.399	V	See schematic.

Table 11: Recommended operating conditions.

10.3 Physical Dimensions

- Module size: 40 × 56.4 mm. Please download the assembly diagram for exact numbers.
- Mating height with standard connectors: 5 mm
- PCB thickness: 2.0 mm ±10 %

All dimensions are shown in millimeters.

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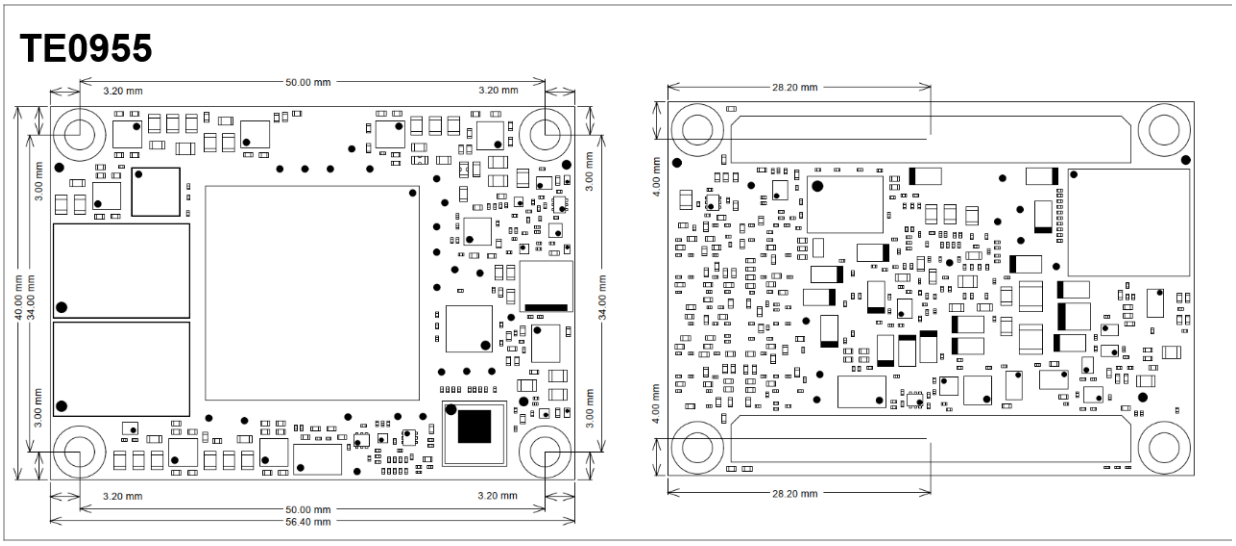

Figure 3: Physical Dimension

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11 Currently Offered Variants

Trenz shop TE0955 overview page*	
English page	German page

Table 12: Trenz Electronic Shop Overview
*) Module article name encoding table: AMD Versal based modules

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12 Revision History

12.1 Hardware Revision History

The hardware revision number is located on the PCB next to the module identifier, separated by a dash.

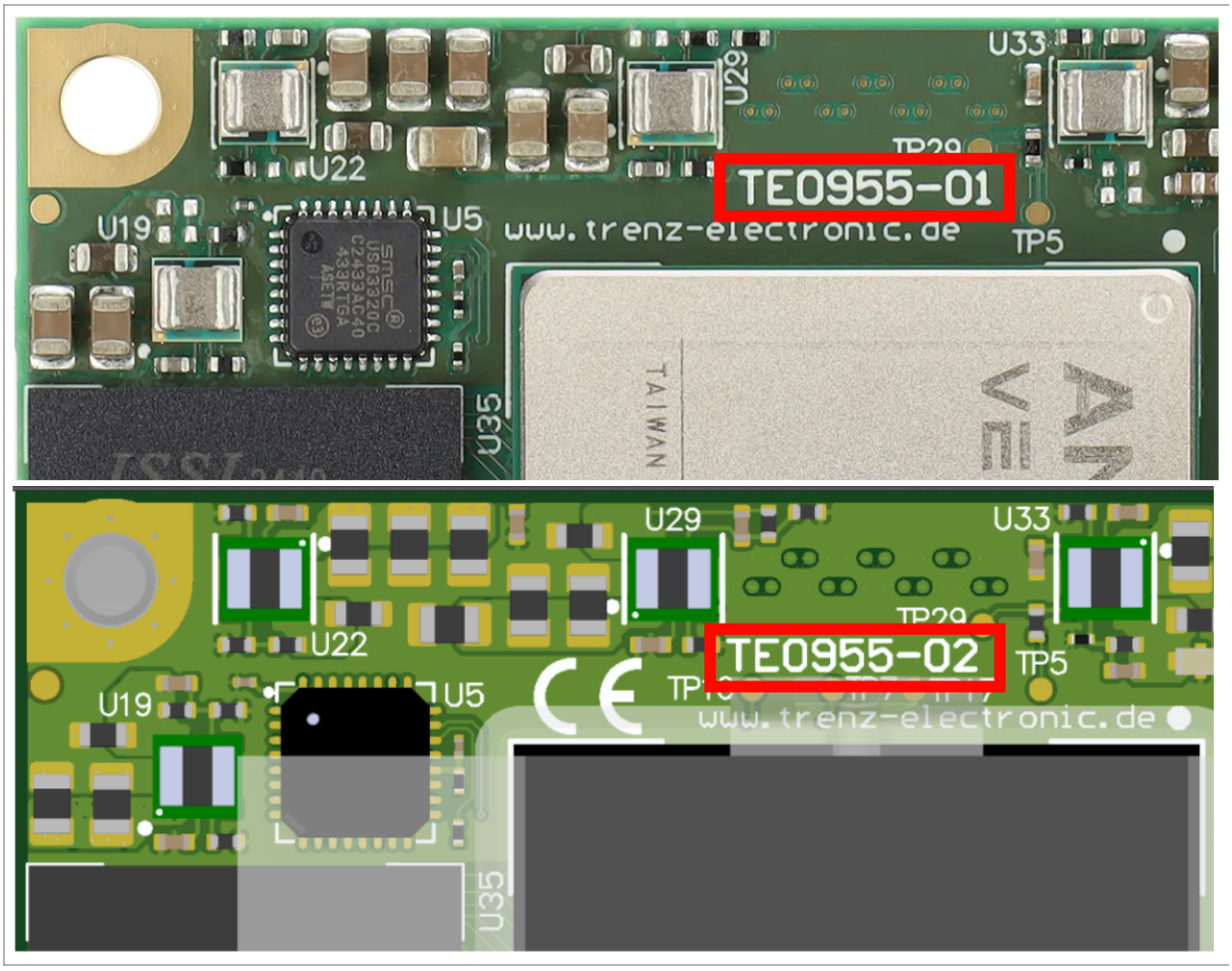

Figure 4: Board hardware revision number.

Date	Revision	Changes	Documentation Link
2025-12	REV02	1. Set R156 to assembled and connected to GTYP_AVCC_AUX rail instead of 1V8. Removed patch including R156_NEW. 2. Corrected and updated silkscreen description of Connectors JM5 and JM6 to show also Andromeda connector naming W and X. Removed corresponding schematic notes. 3. Moved serial sticker from bottom to top. Now placed on Ethernet PHY U3. 4. Removed unnecessary zero Ohm R159. 5. Replaced 0402 resistor R157 by 0201 size version. 6. Moved R52 and R74 away from PCB edge/tab. 7. Moved R14, R16, R19, R60, R64, R79, C19,C52 C186 C194, C196, C203 L11 away from ATS holder area. 8. Replaced buffers U7, U10, U16, U25 from 74LVC2G07FZ4-7 to SN74LVC2G07DSF2 9. Added TPM module U37 with corresponding circuits 10. Added option for additional pullups (not fitted: R196, R197) on OM_I2C bus 11. Moved Testpoints: TP7, TP9, TP13, TP16, TP20, TP21, TP27 12. Updated schematic overview page template 13. Added Note that U14, U15 may be removed in future. 14. Added OSPI assembly option (R198, R199) to use MIO12 as dedicated reset instead of ECS#. 15. Change ETH PHY from LAN8830 to LAN8840 to support TSN/PTP	REV02
2025-02	REV01	Initial release	REV01

Table 13: Hardware Revision History

12.2 Document Change History

Date	Revision	Contributor	Description
2026-02-26	v.7	Kilian Jahn	• Corrected minor errors

Date	Revision	Contributor	Description
2026-01-23	v.6	Martin Rohrmüller	• Updated to REV02
20.01.2026	v.4	Martin Rohrmüller	• Corrected Typo in block diagram
24.10.2025	v.2	Kilian Jahn	• Initial TRM in template revision 4.3.2
--	all	Kilian Jahn , Martin Rohrmüller	• --

Table 14: Document change history.

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13 Disclaimer

13.1 Data Privacy

Please also note our data protection declaration at https://www.trenz-electronic.de/en/Data-protection-Privacy

13.2 Document Warranty

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13.5 Copyright Notice

No part of this manual may be reproduced in any form or by any means (including electronic storage and retrieval or translation into a foreign language) without prior agreement and written consent from Trenz Electronic.

13.6 Technology Licenses

The hardware / firmware / software described in this document are furnished under a license and may be used /modified / copied only in accordance with the terms of such license.

13.7 Environmental Protection

To confront directly with the responsibility toward the environment, the global community and eventually also oneself. Such a resolution should be integral part not only of everybody's life. Also enterprises shall be conscious of their social responsibility and contribute to the preservation of our common living space. That is why Trenz Electronic invests in the protection of our Environment.

13.8 REACH, RoHS and WEEE

REACH

Trenz Electronic is a manufacturer and a distributor of electronic products. It is therefore a so called downstream user in the sense of REACH. The products we supply to you are solely non-chemical products (goods). Moreover and under normal and reasonably foreseeable circumstances of application, the goods supplied to you shall not release any substance. For that, Trenz Electronic is obliged to neither register nor to provide safety data sheet. According to present knowledge and to best of our knowledge, no SVHC (Substances of Very High Concern) on the Candidate List are contained in our products. Furthermore, we will immediately and unsolicited inform our customers in compliance with REACH - Article 33 if any substance present in our goods (above a concentration of 0,1 % weight by weight) will be classified as SVHC by the European Chemicals Agency (ECHA).

RoHS

Trenz Electronic GmbH herewith declares that all its products are developed, manufactured and distributed RoHS compliant.

WEEE

Information for users within the European Union in accordance with Directive 2002/96/EC of the European Parliament and of the Council of 27 January 2003 on waste electrical and electronic equipment (WEEE).

Users of electrical and electronic equipment in private households are required not to dispose of waste electrical and electronic equipment as unsorted municipal waste and to collect such waste electrical and electronic equipment separately. By the 13 August 2005, Member States shall have ensured that systems are set up allowing final holders and distributors to return waste electrical and electronic equipment at least free of charge. Member States shall ensure the availability and accessibility of the necessary collection facilities. Separate collection is the precondition to ensure specific treatment and recycling of waste electrical and electronic equipment and is necessary to achieve the chosen level of protection of human health and the environment in the European Union. Consumers have to actively contribute to the success of such collection and the return of waste electrical and electronic equipment. Presence of hazardous substances in electrical and electronic equipment results in potential effects on the environment and human health. The symbol consisting of the crossed-out wheeled bin indicates separate collection for waste electrical and electronic equipment.

Trenz Electronic is registered under WEEE-Reg.-Nr. DE97922676.

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